

IN THE CLAIMS:

Please cancel claims 13-19 without prejudice or disclaimer to the subject matter recited therein.

Please add the following claims:

--23. A surface laminar circuit board, comprising:
an insulating layer;
a sheet of conductive material disposed on an upper surface of said insulating layer, said sheet of conductive material having a hole formed therein, the hole exposing a portion of said insulating layer, the sheet of conductive material completely surrounding an area defined by the hole, the area being in registration with, and corresponding in shape and size, to the portion of said insulating layer exposed by the hole;
a dielectric layer disposed on an upper surface of said conductive material; and
a conductive pad having a major portion thereof disposed directly over the portion of said insulating layer exposed by the hole, said conductive pad being for receiving a surface mounted component thereon.

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24. The surface laminar circuit board of claim 23, wherein said dielectric layer is in direct contact with the portion of said insulating layer exposed by the hole, and wherein said conductive pad is disposed in direct contact with an upper surface of said

dielectric layer, said dielectric layer separating said conductive pad from said conductive material and from said insulating layer.

25. The surface laminar circuit board of claim 23, wherein said conductive material comprises a signal ground layer.

26. The surface laminar circuit board of claim 25, wherein said dielectric layer has a thickness, in a region over said conductive material, less than about 50 micrometers.

27. The surface laminar circuit board of claim 25, wherein said dielectric layer has a thickness, in a region over said conductive material, equal to or less than about 40 micrometers.

28. The surface laminar circuit board of claim 25, wherein all of said conductive pad is disposed over the portion of said insulating layer exposed by the hole.

29. The surface laminar circuit board of claim 23, wherein all of said conductive pad is disposed over the portion of said insulating layer exposed by the hole.--

REMARKS

The Examiner's Action mailed on October 3, 2001 has been received and its contents carefully considered.